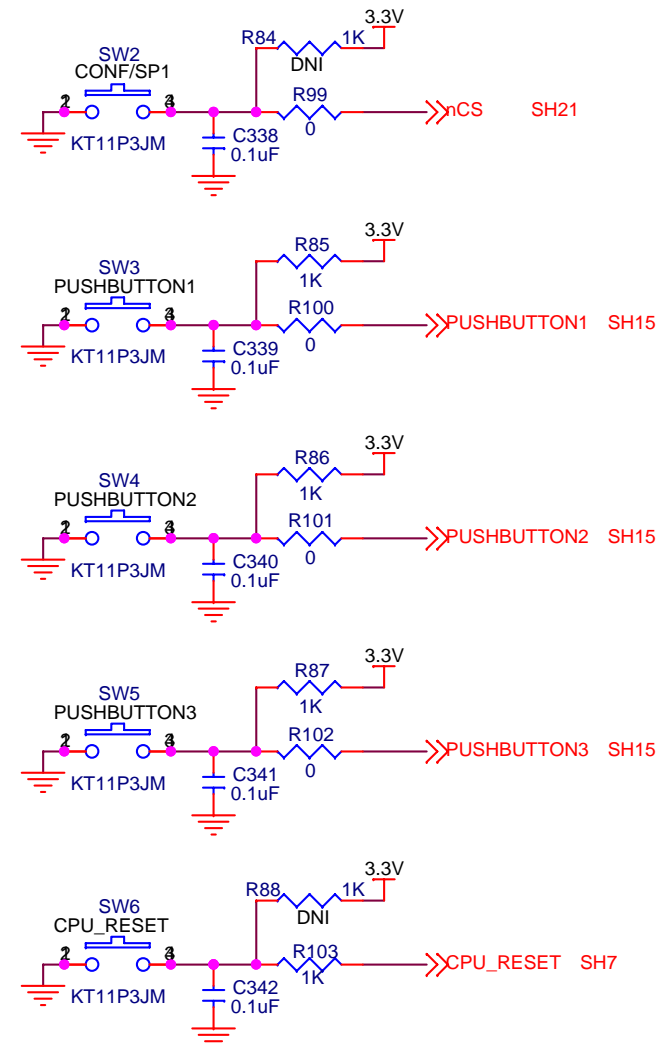
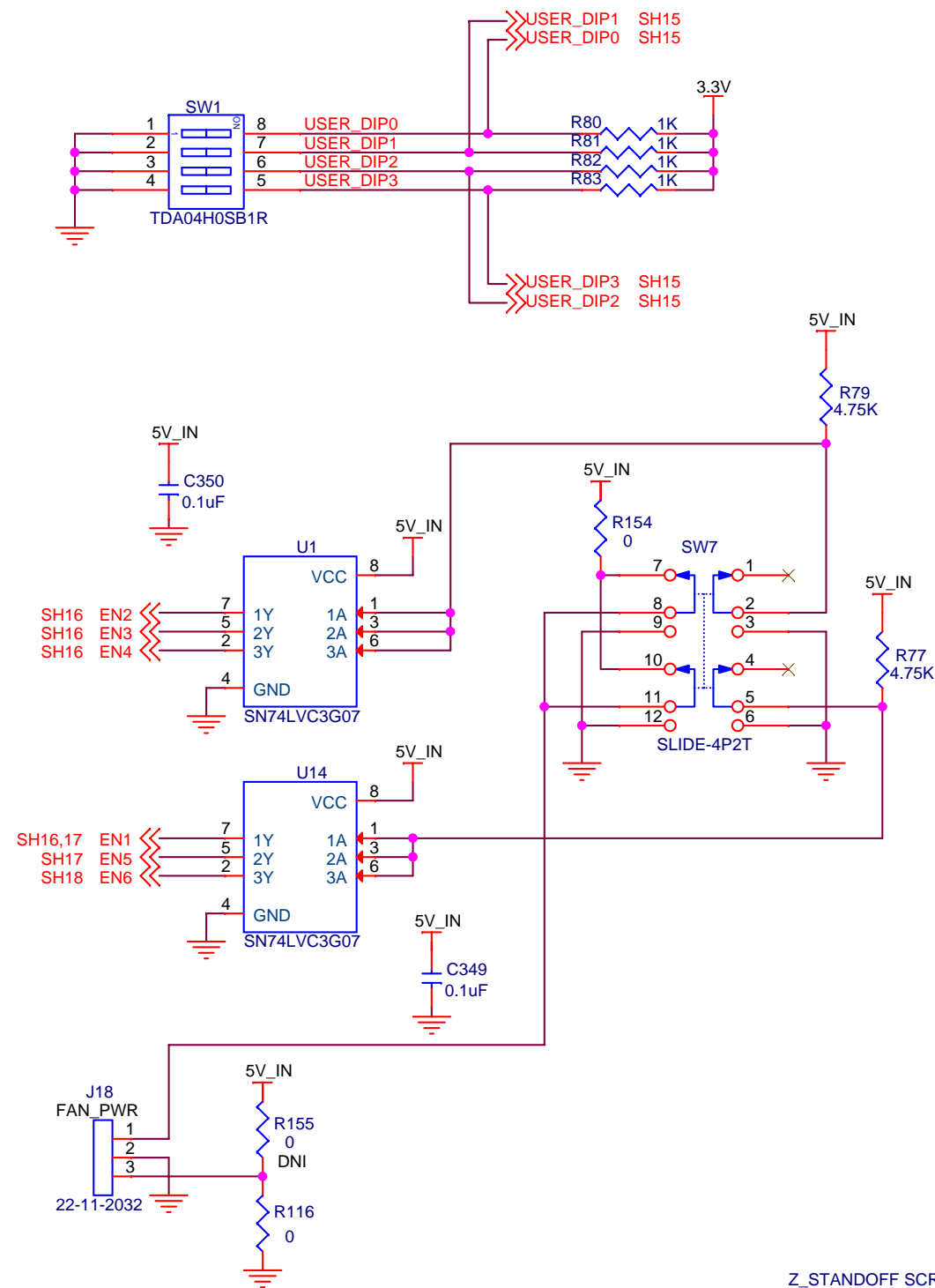
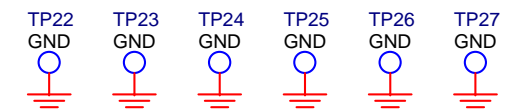
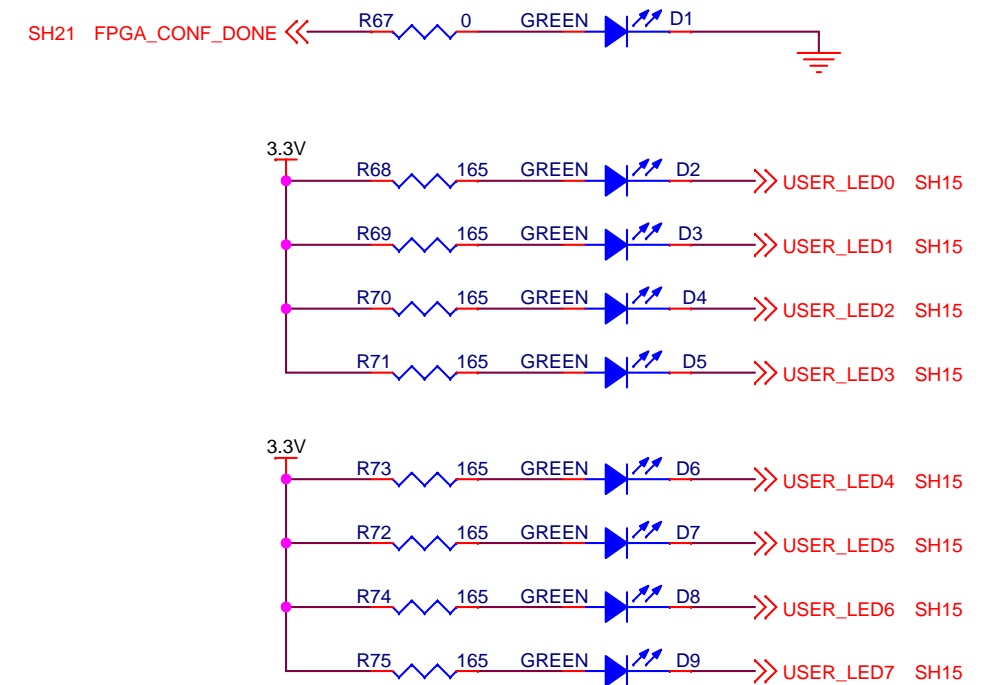


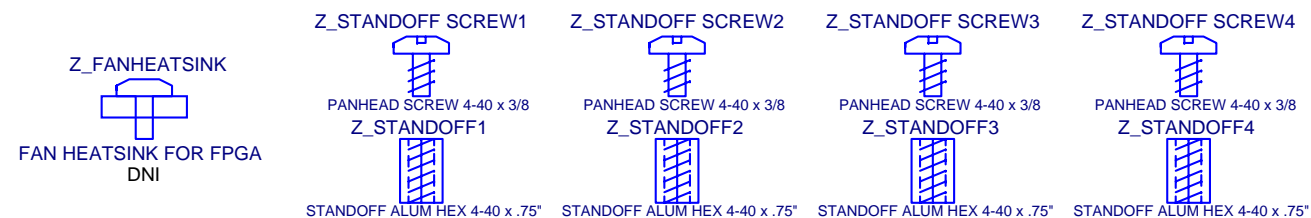
Buttons & Switches



LEDs



MECHANICAL PARTS

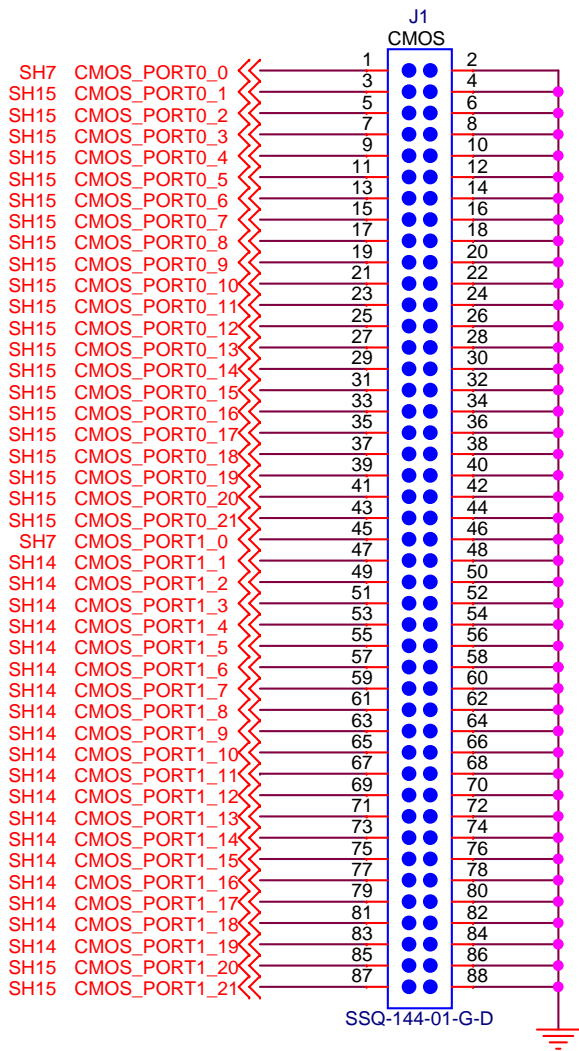


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<i>BUTTONS, SWITCHES, LEDS</i>			
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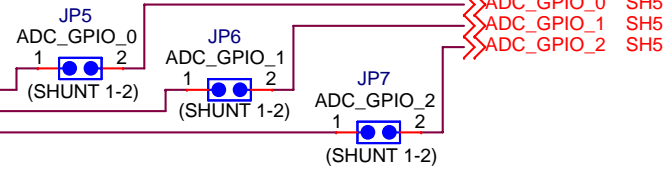
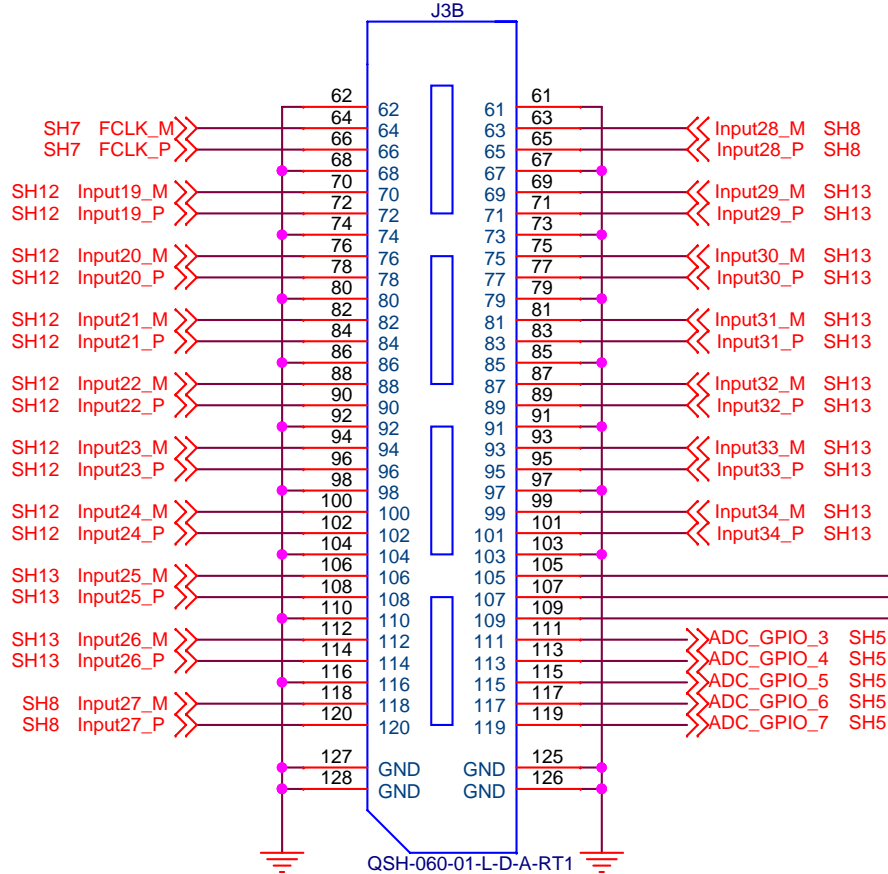
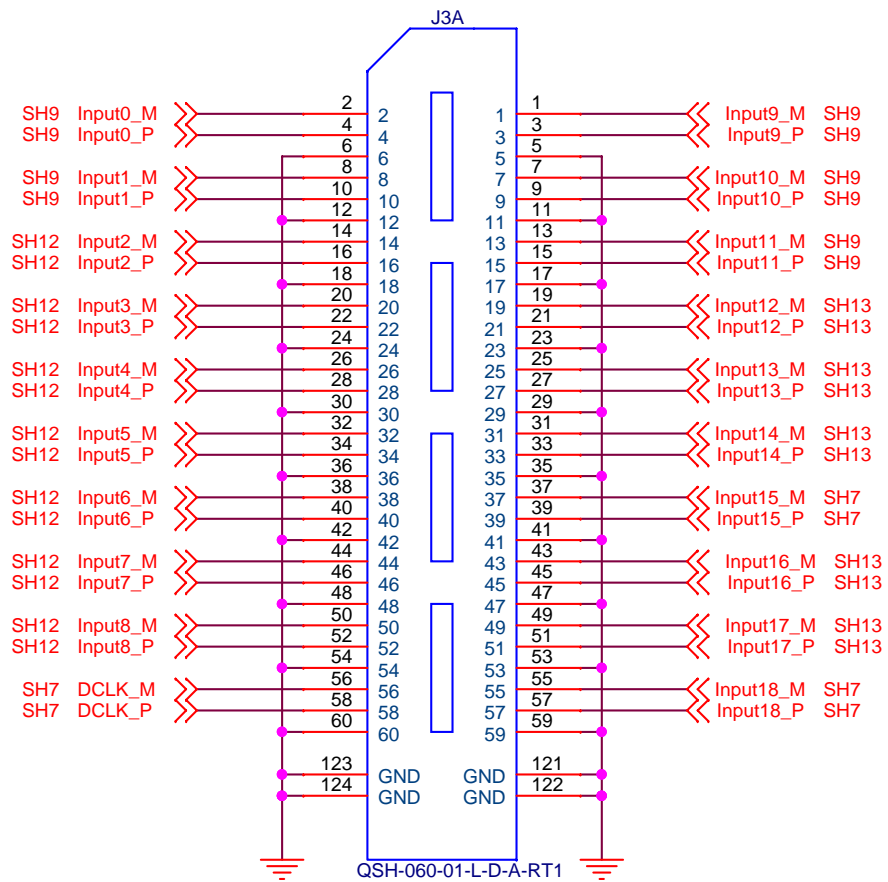
Drawn: P. LARSON

Engineer: J. SETON

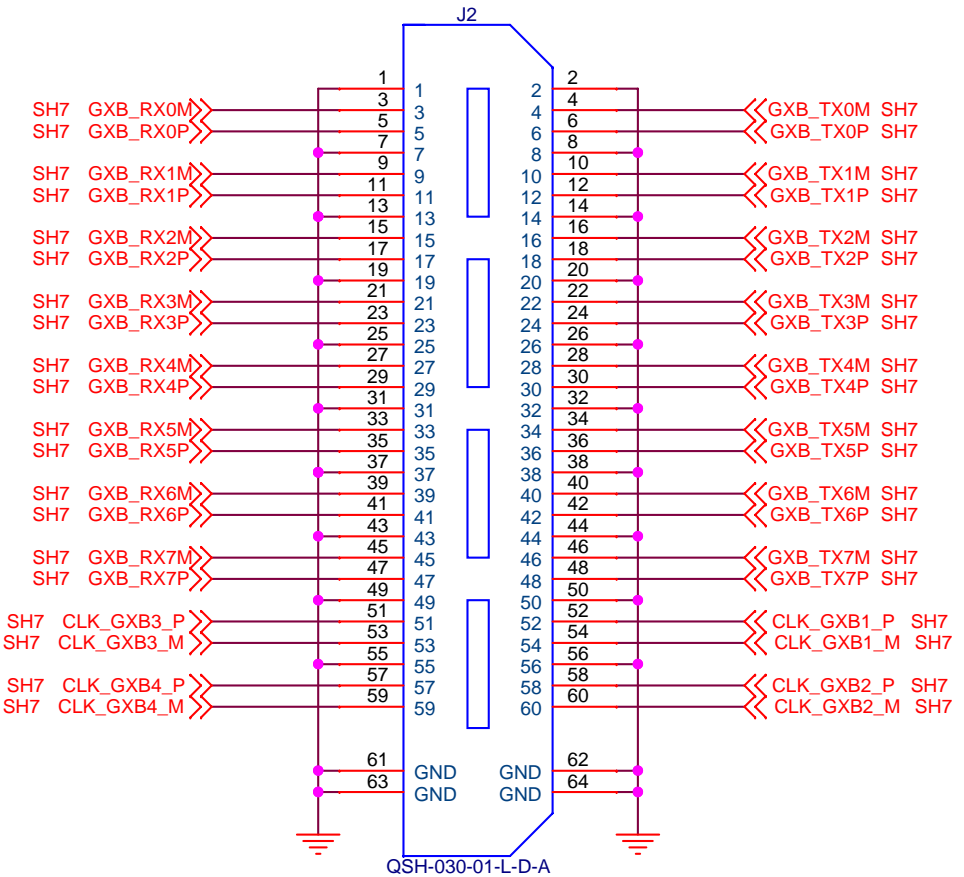
CMOS Header



ADC Interface

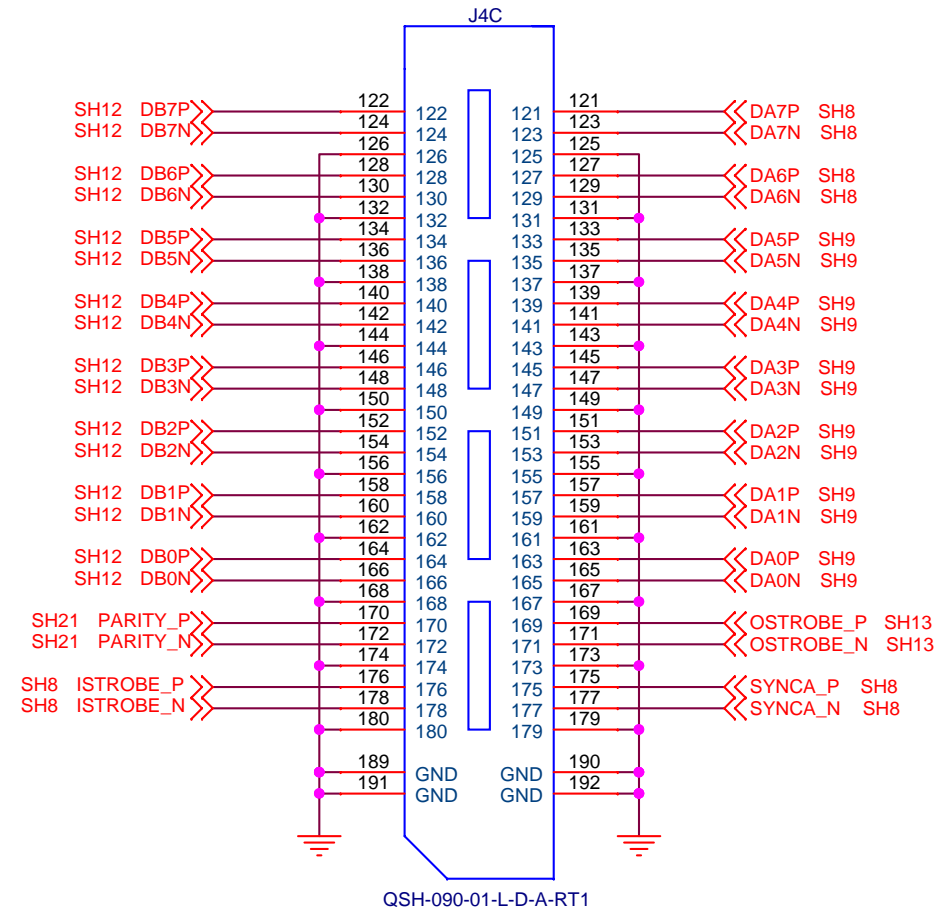
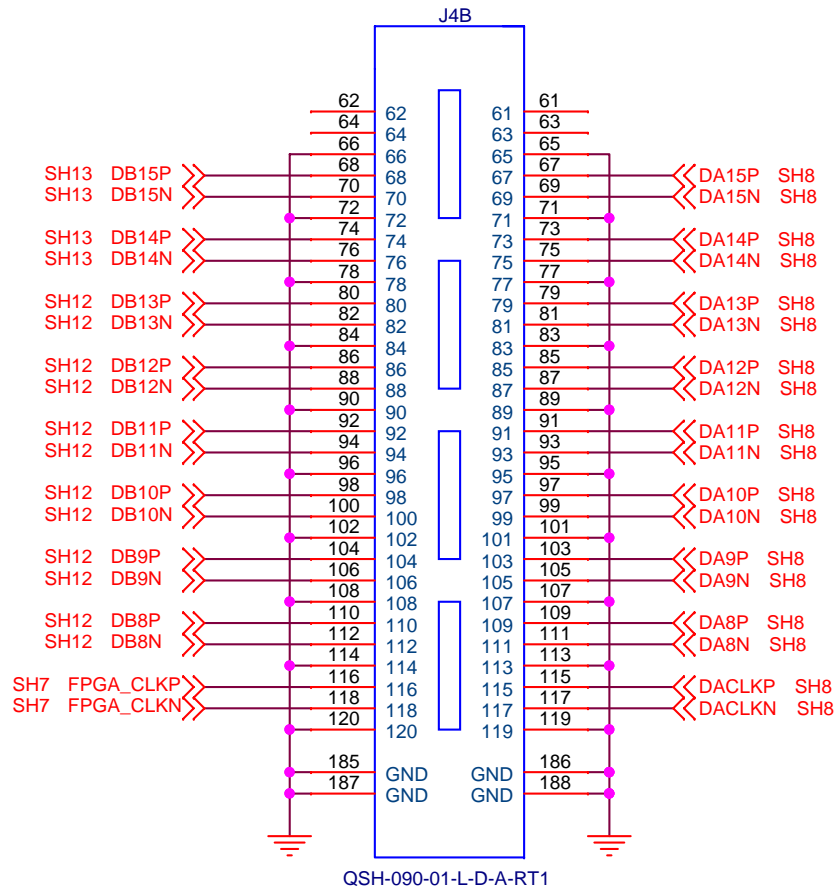
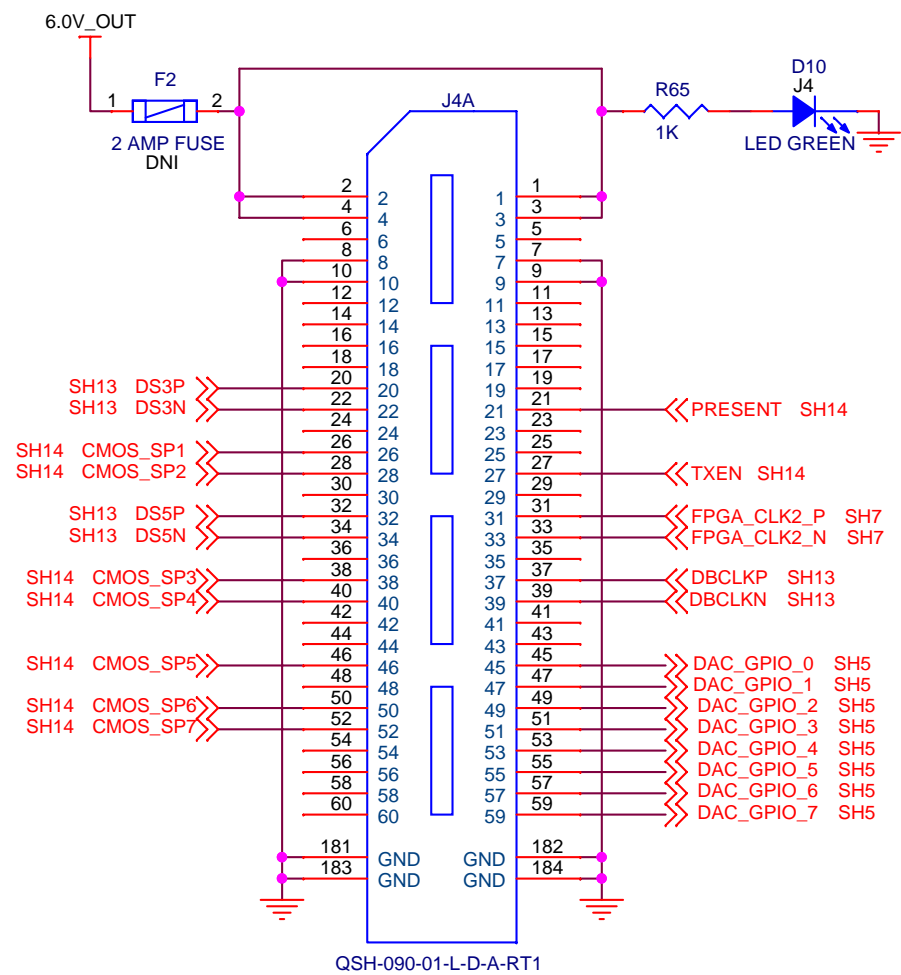


JESD



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DAC Interface

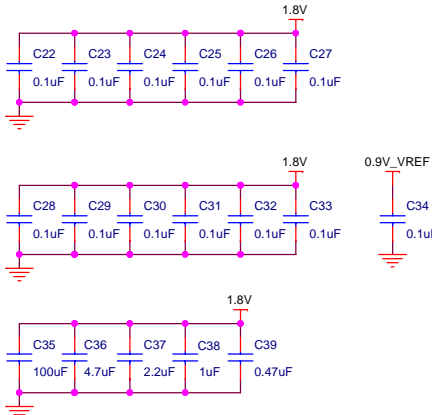
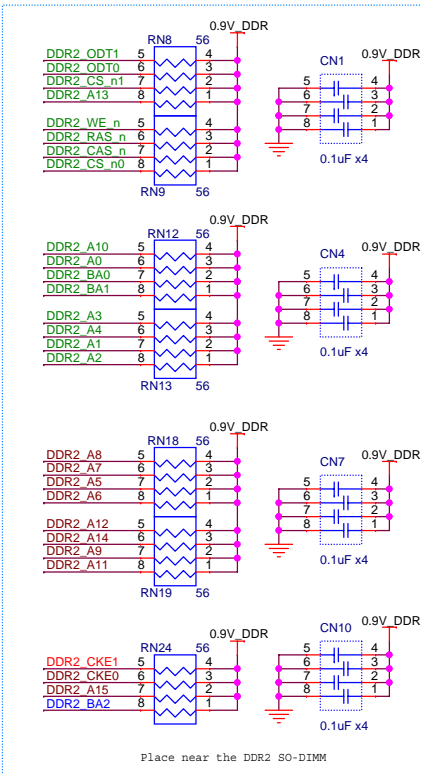
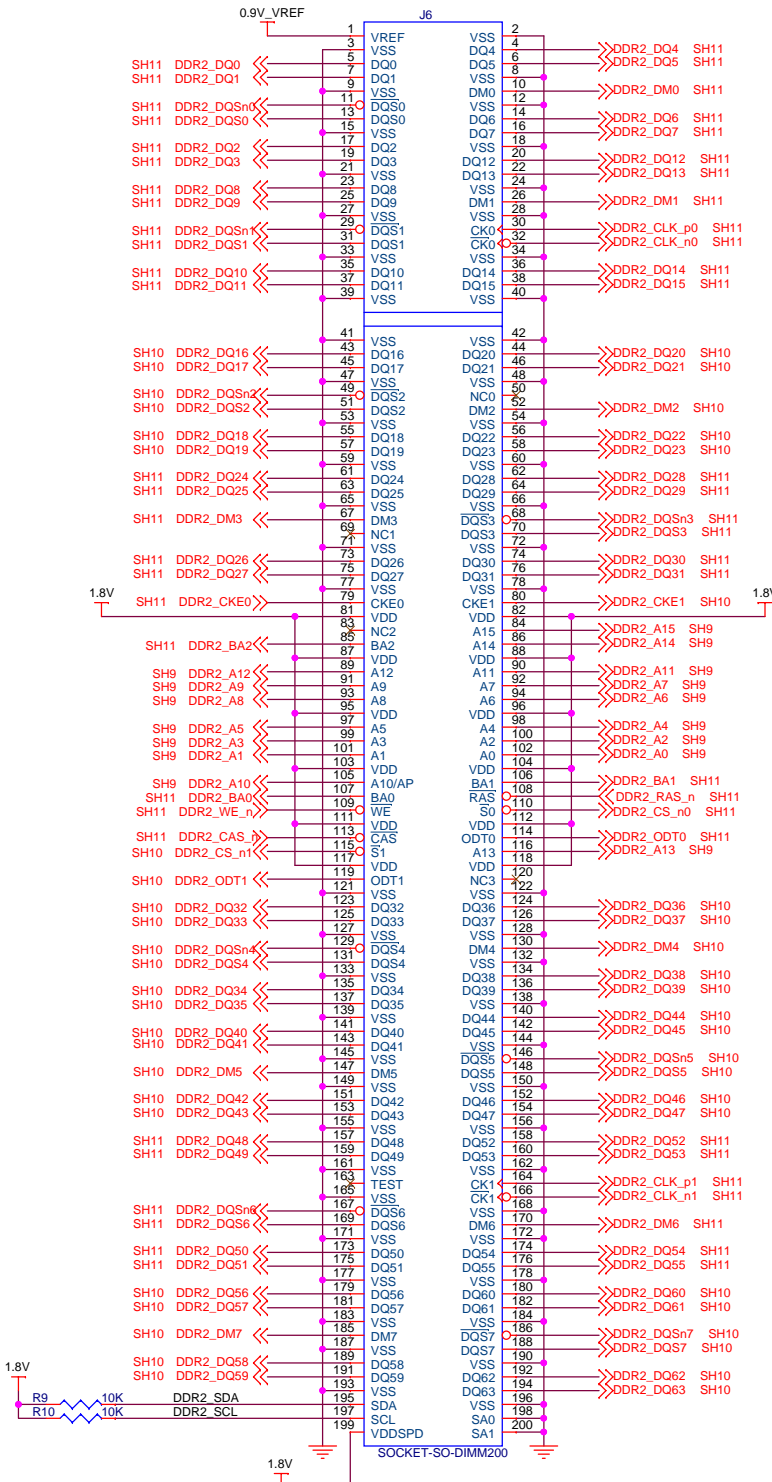


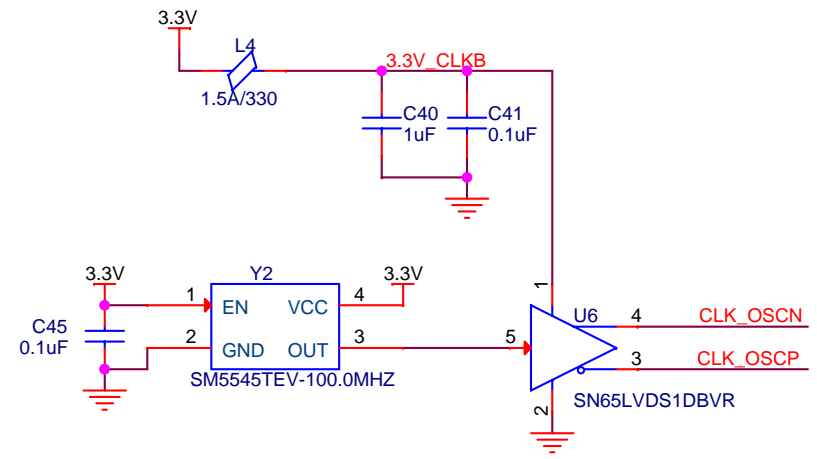
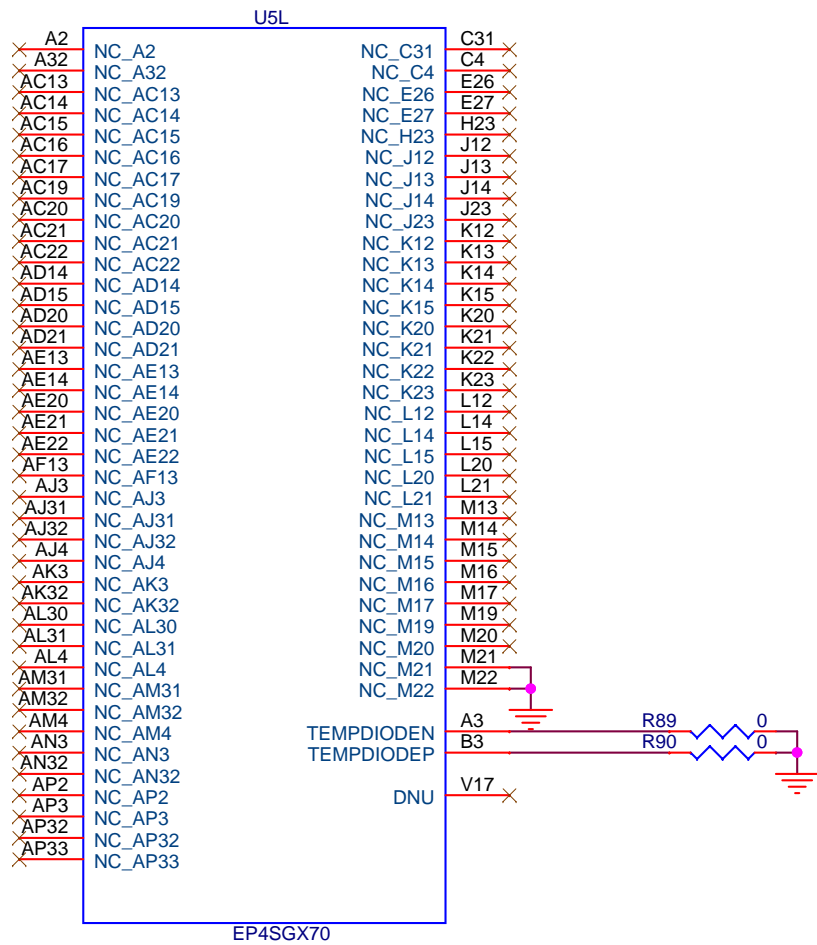
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DAC Interface		
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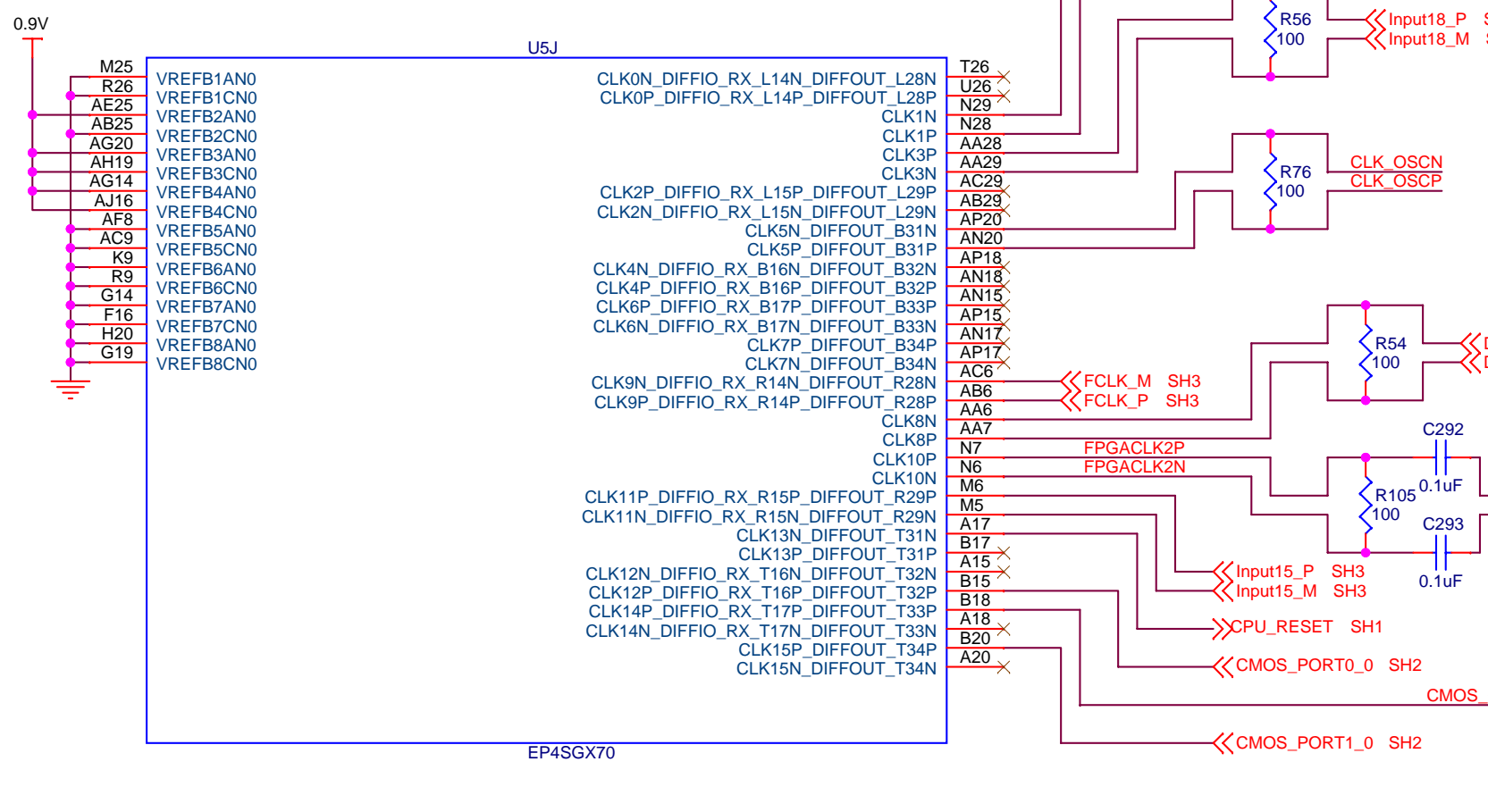
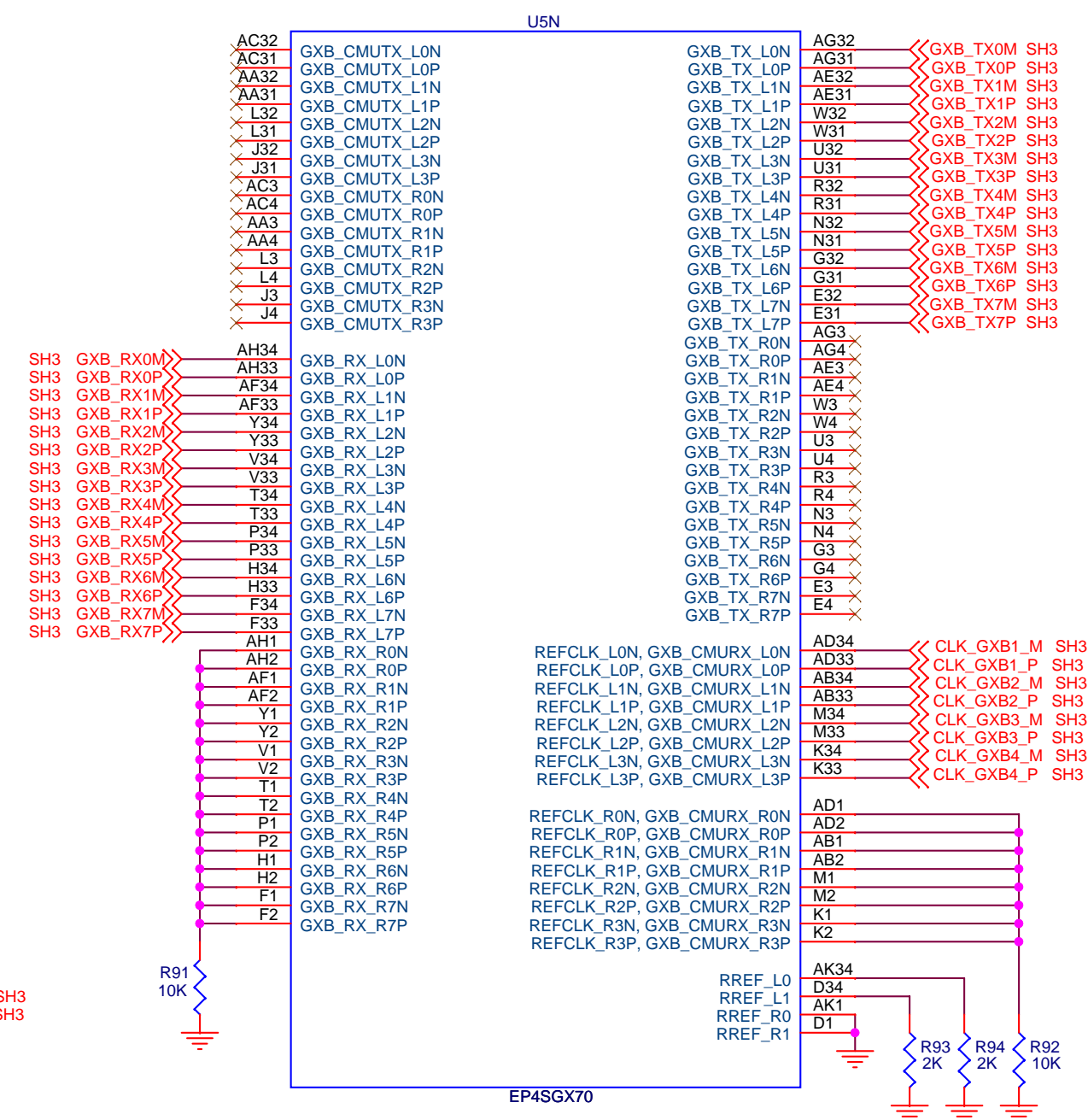
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DDR2 SO-DIMM





BANK QL

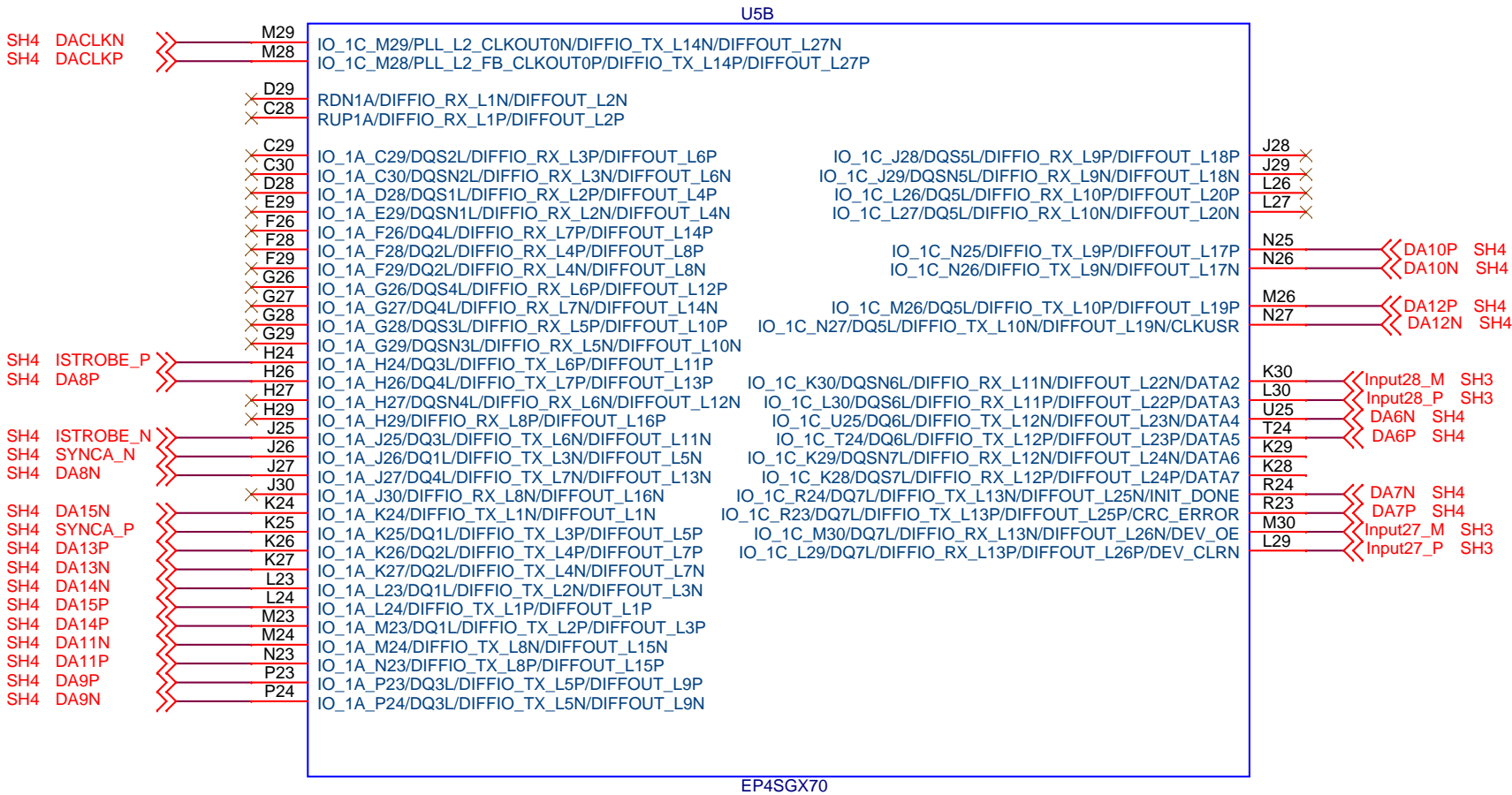




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BANK1
2.5V



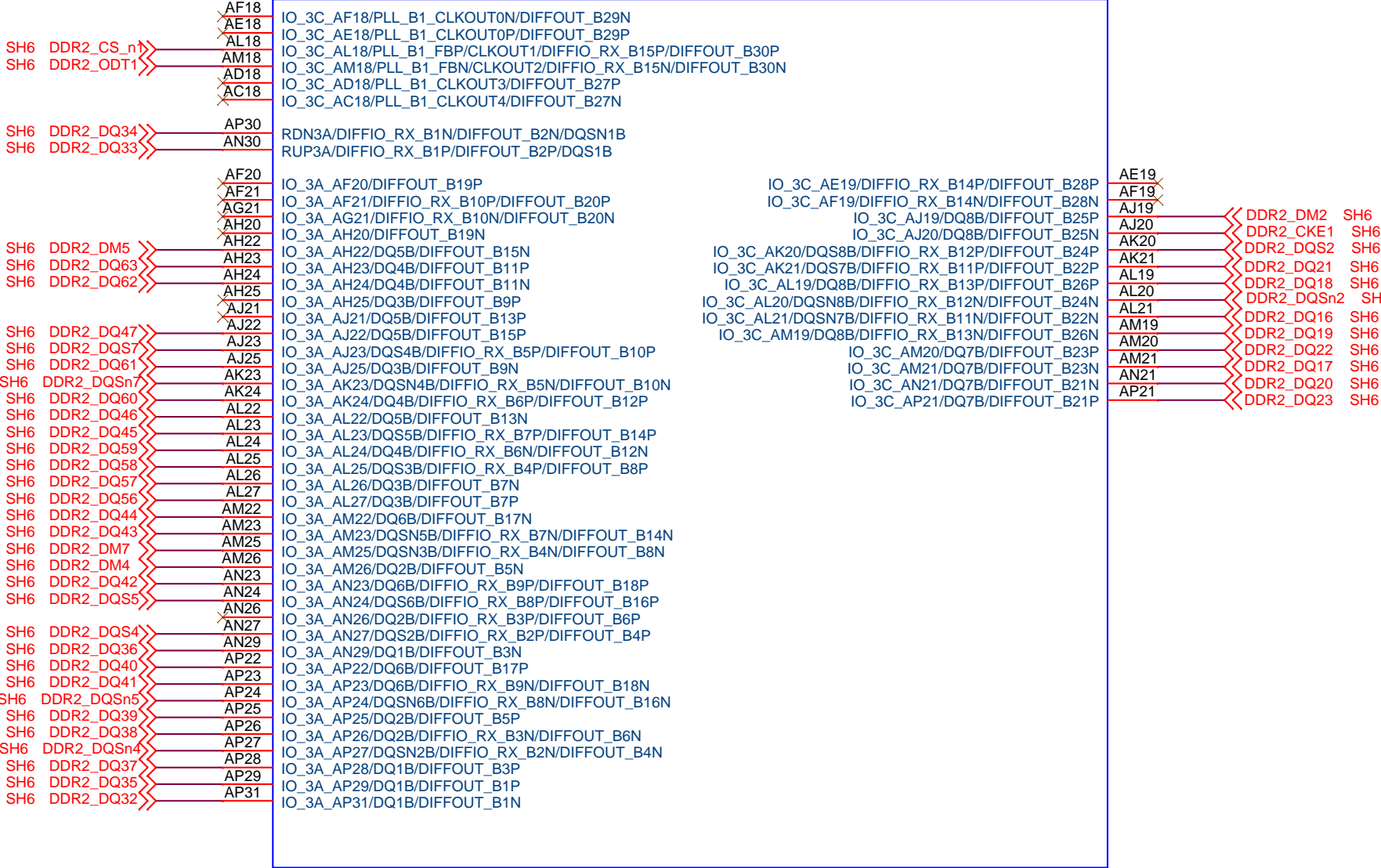
BANK2

1.8V

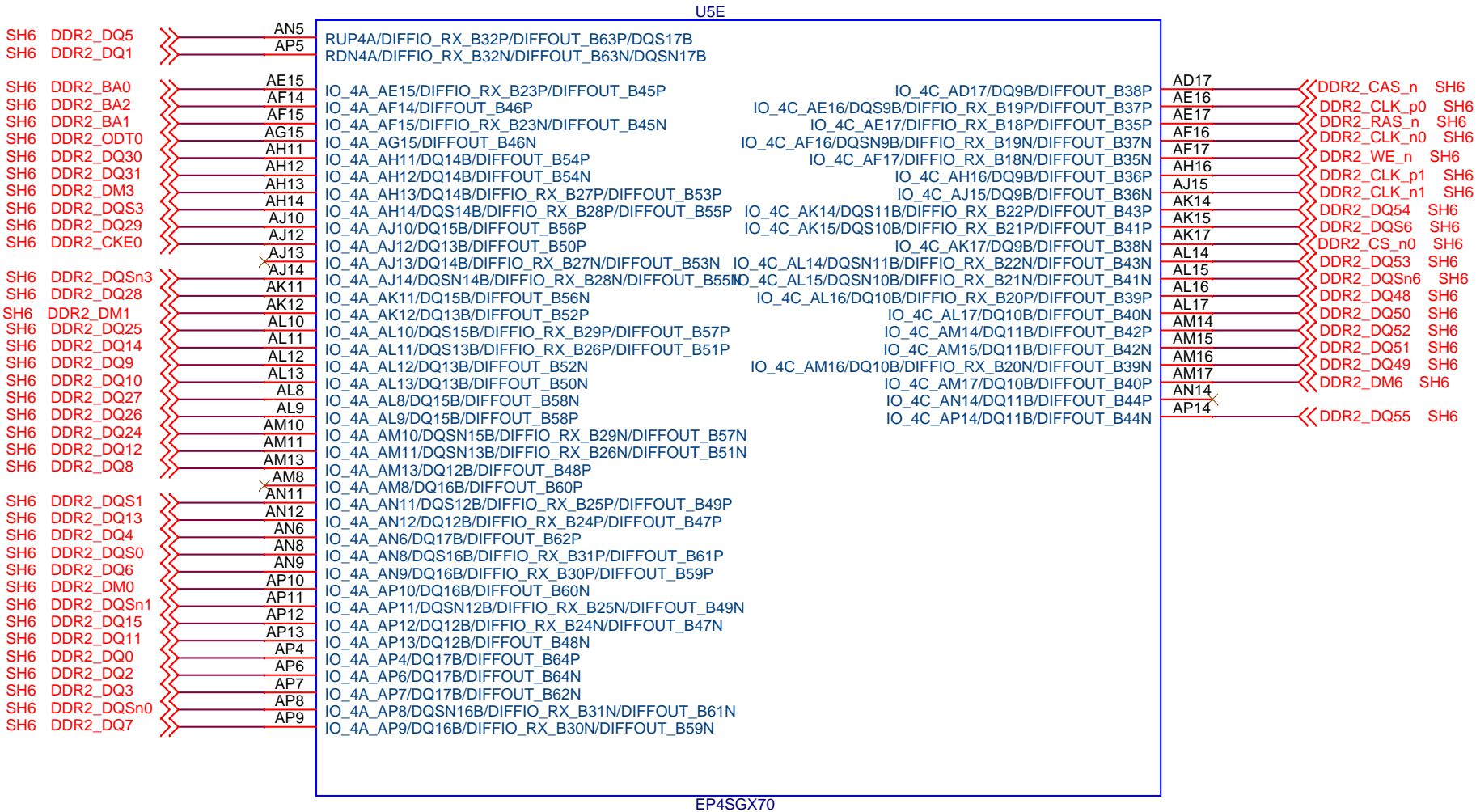
2.5V



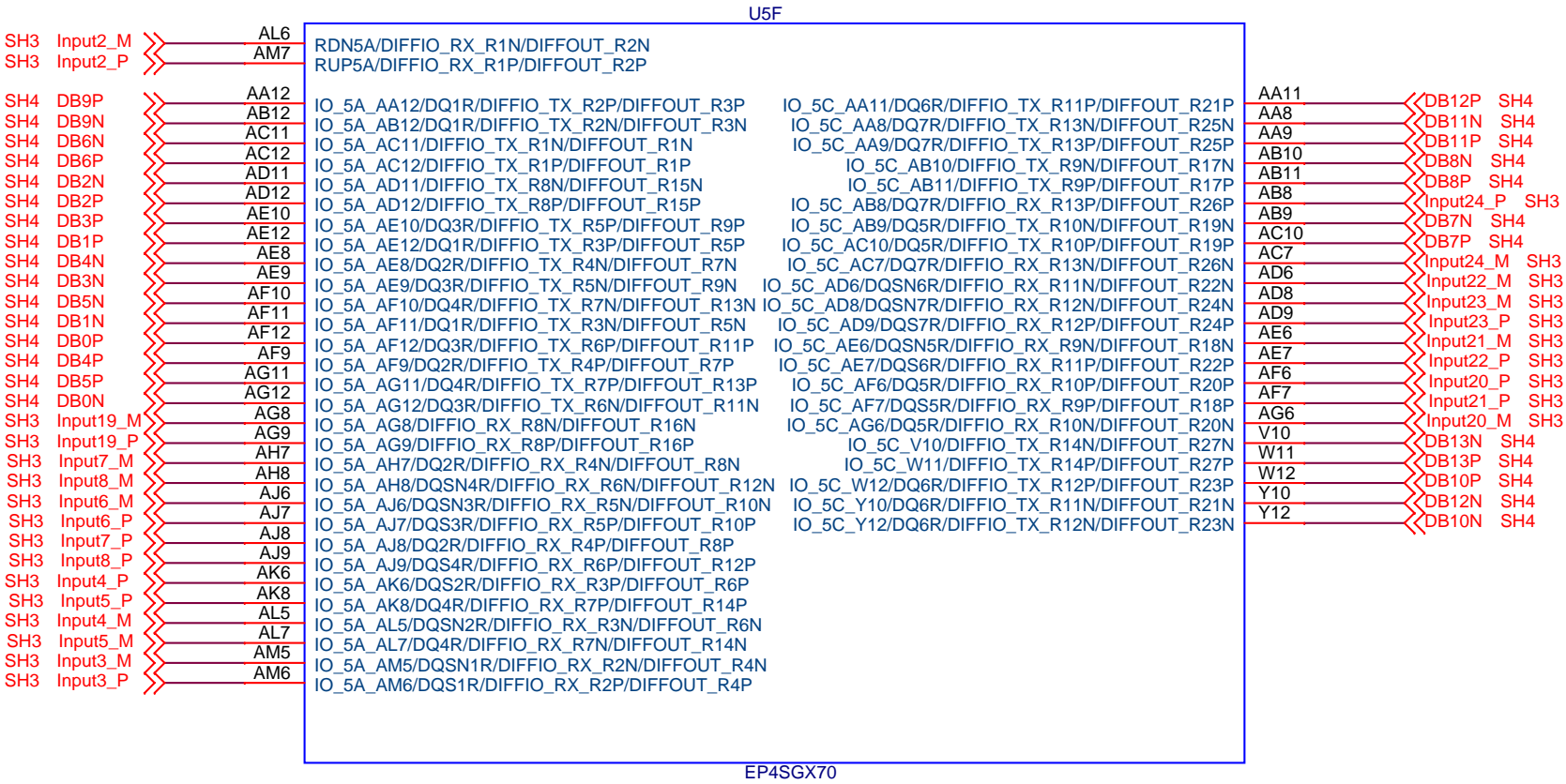
BANK3
1.8V



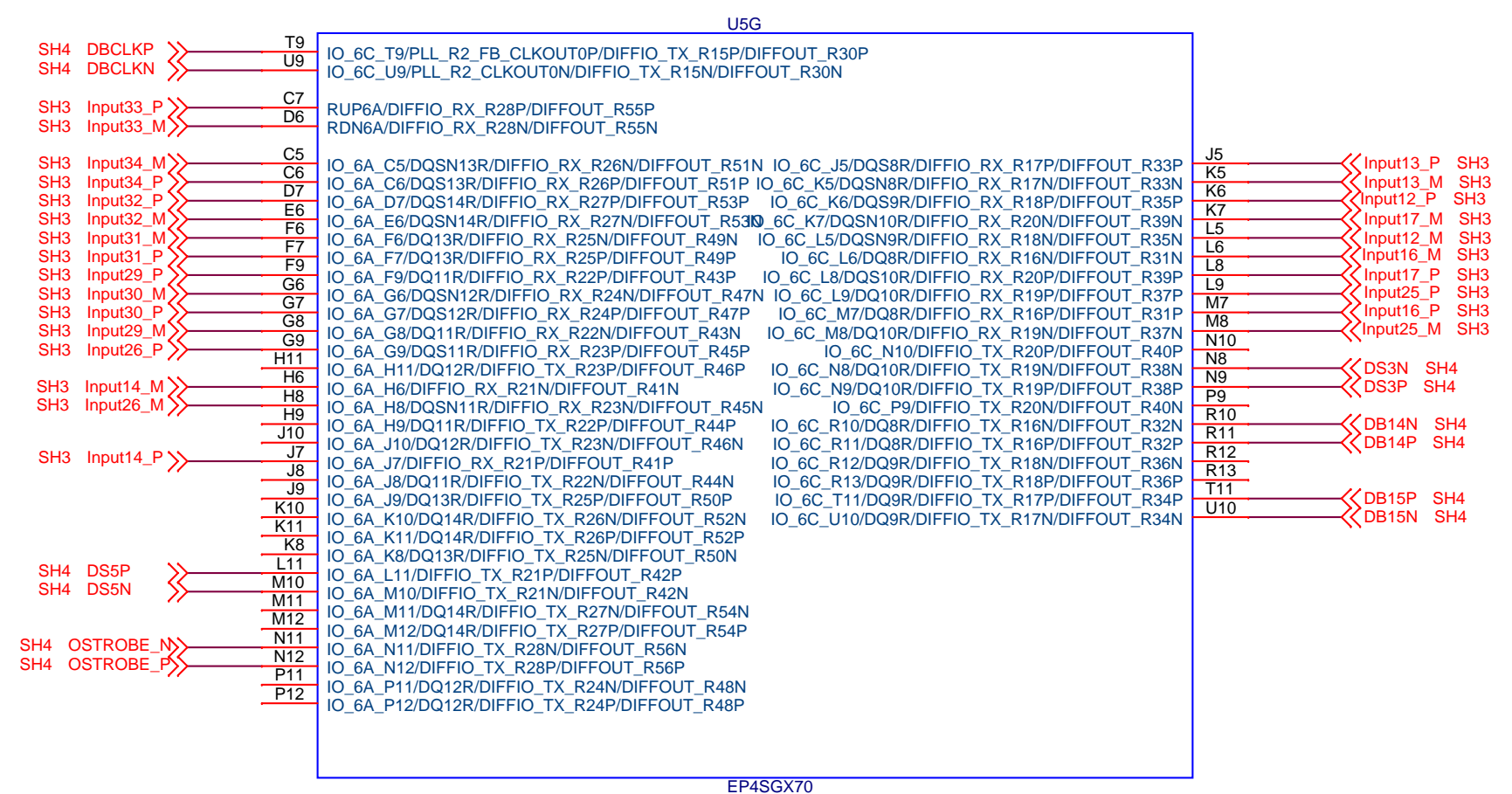
BANK4
1.8V



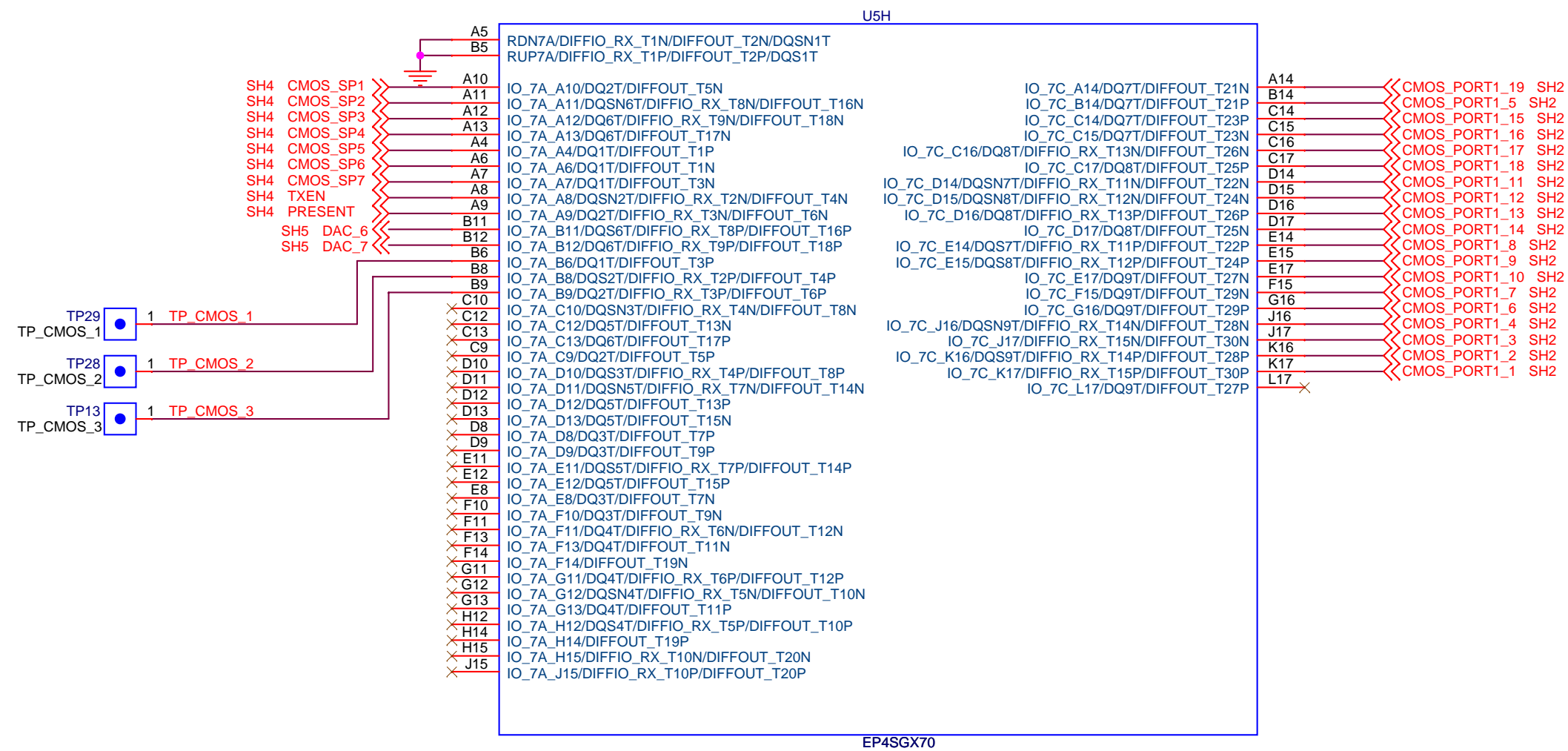
BANK5
2.5V



BANK6
2.5V



BANK7
3.0V



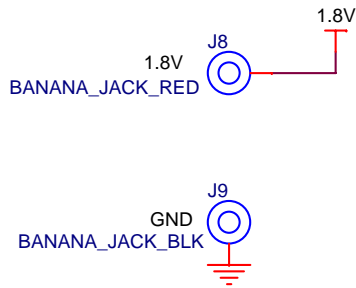
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BANK8
3.0V

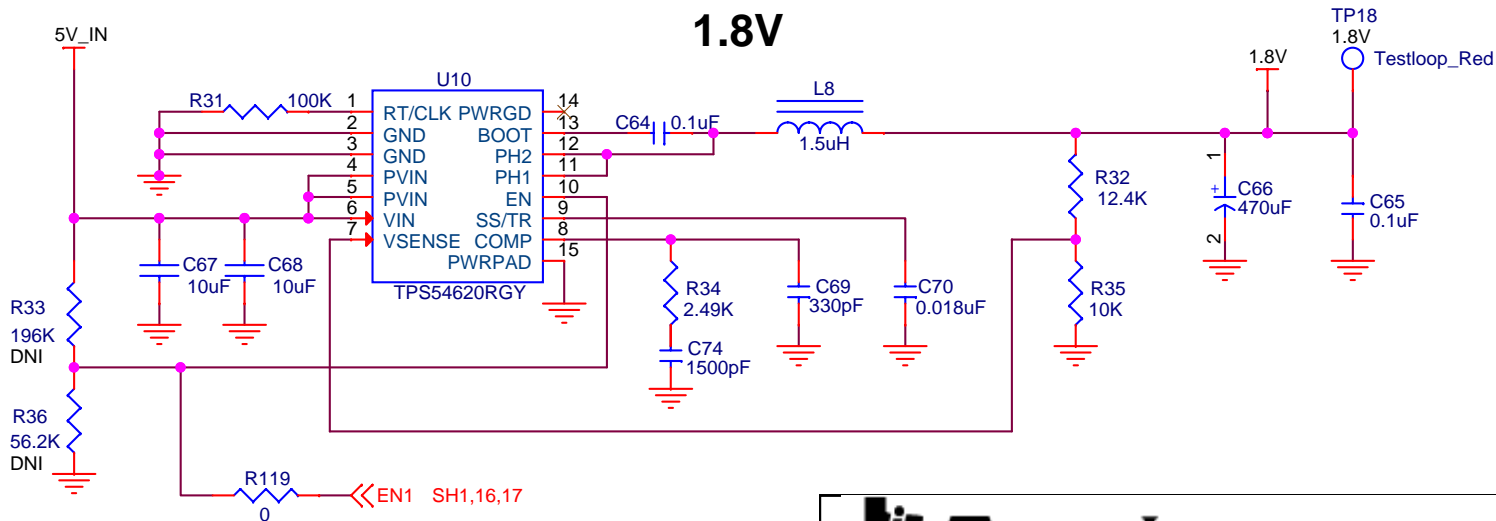
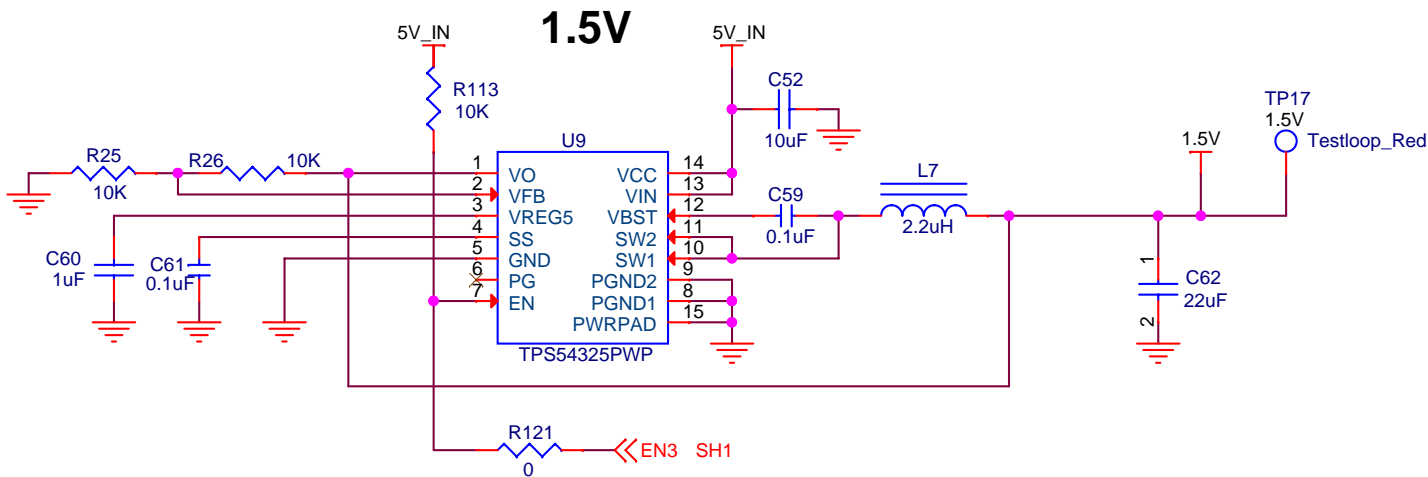
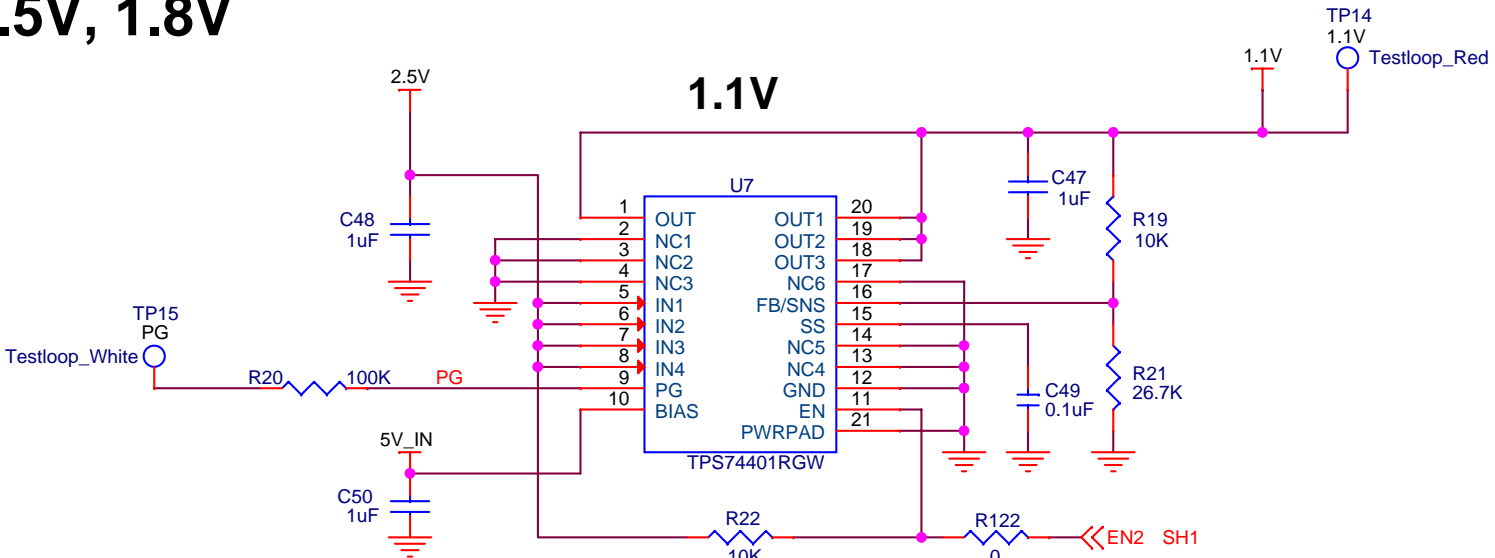
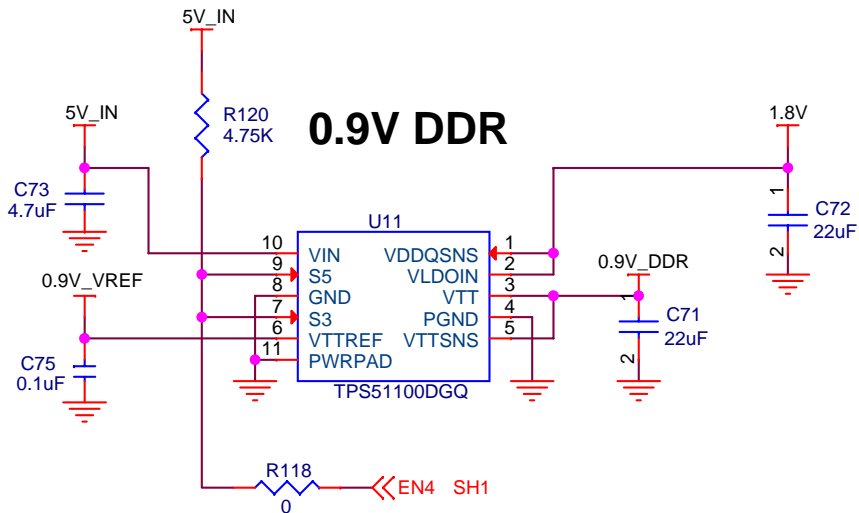
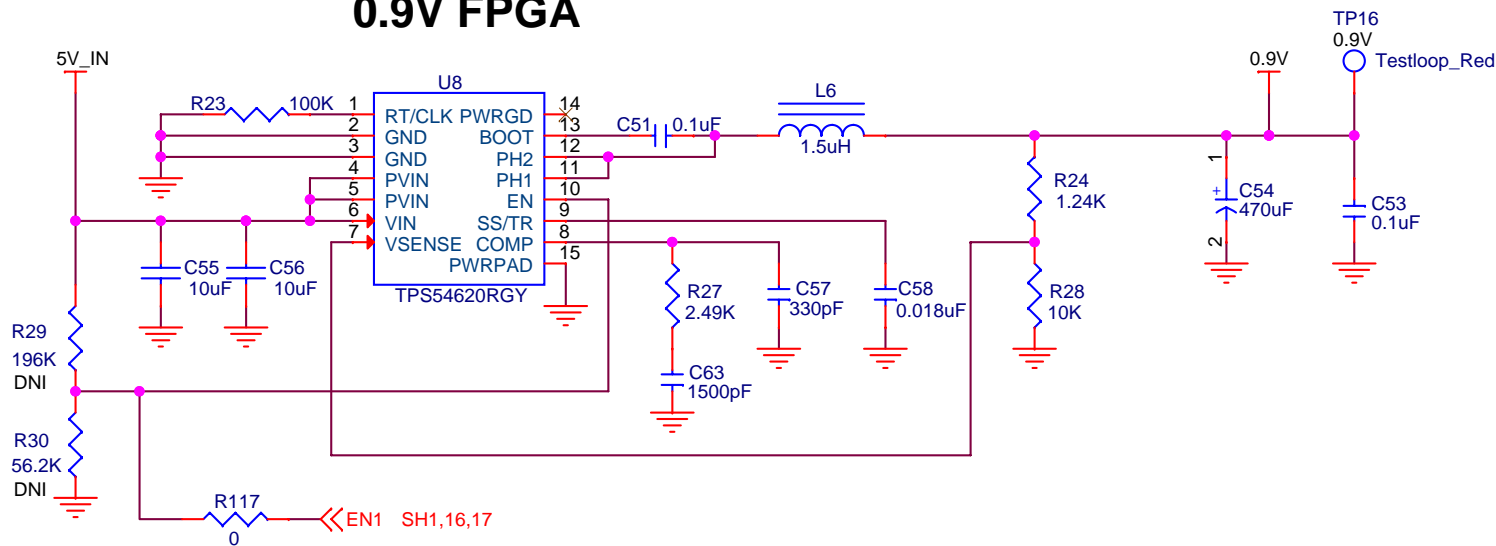


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Bank8		
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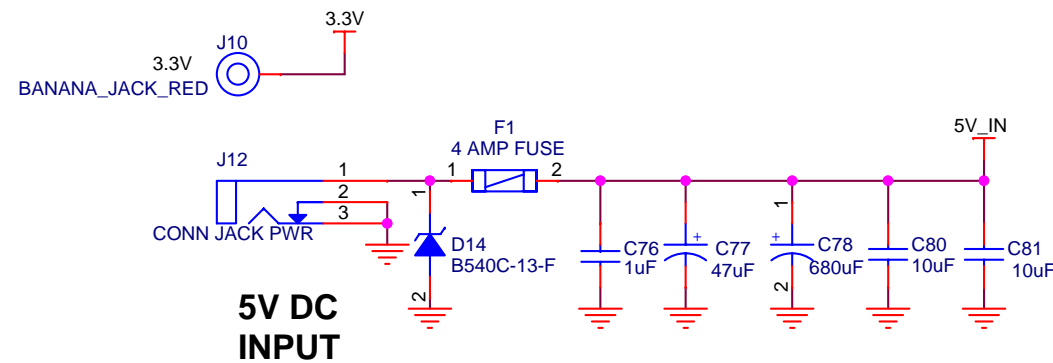
0.9V, 1.1V, 1.5V, 1.8V



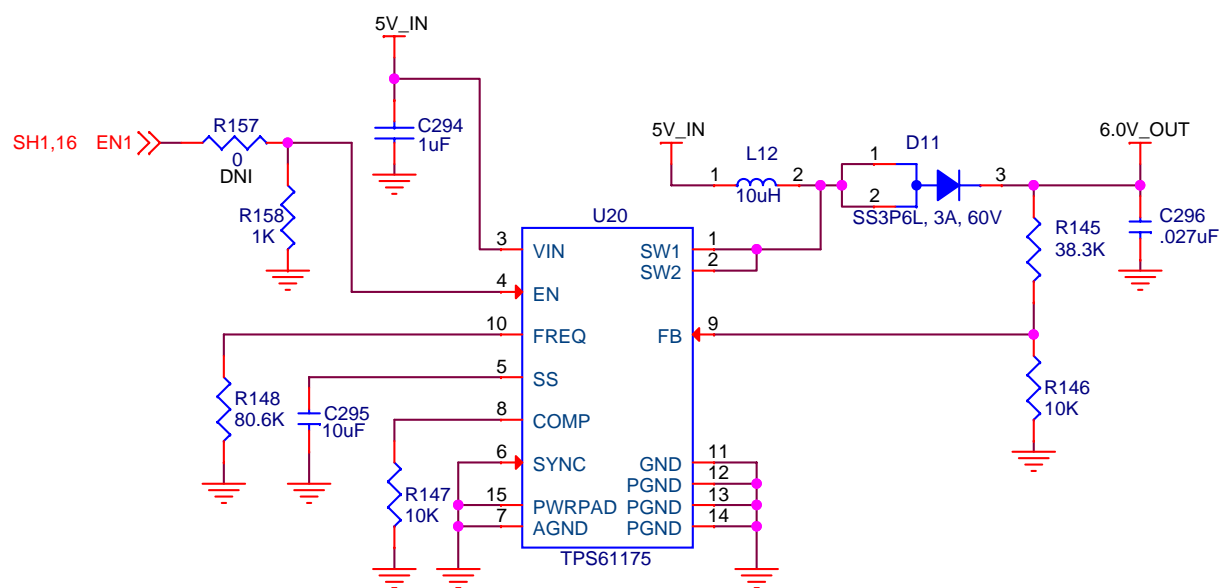
0.9V FPGA



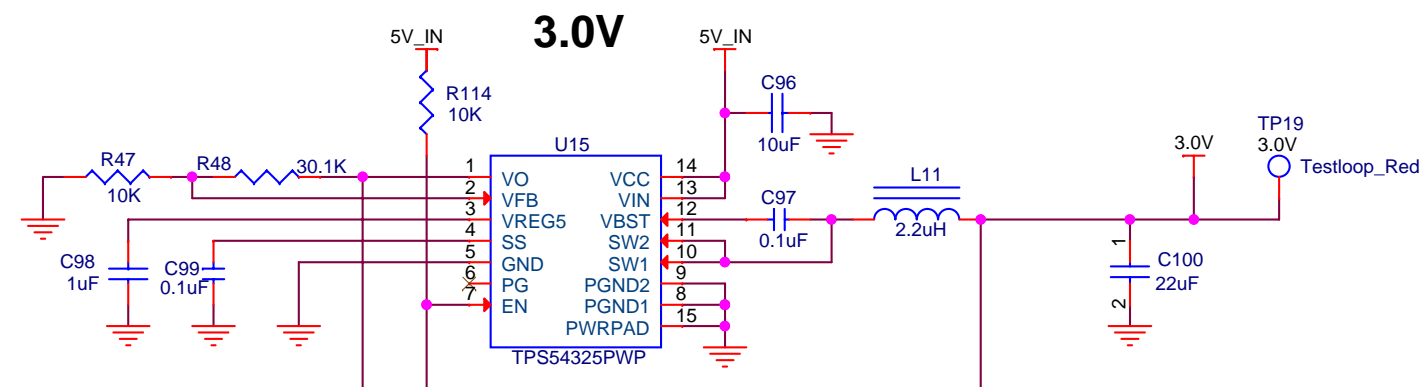
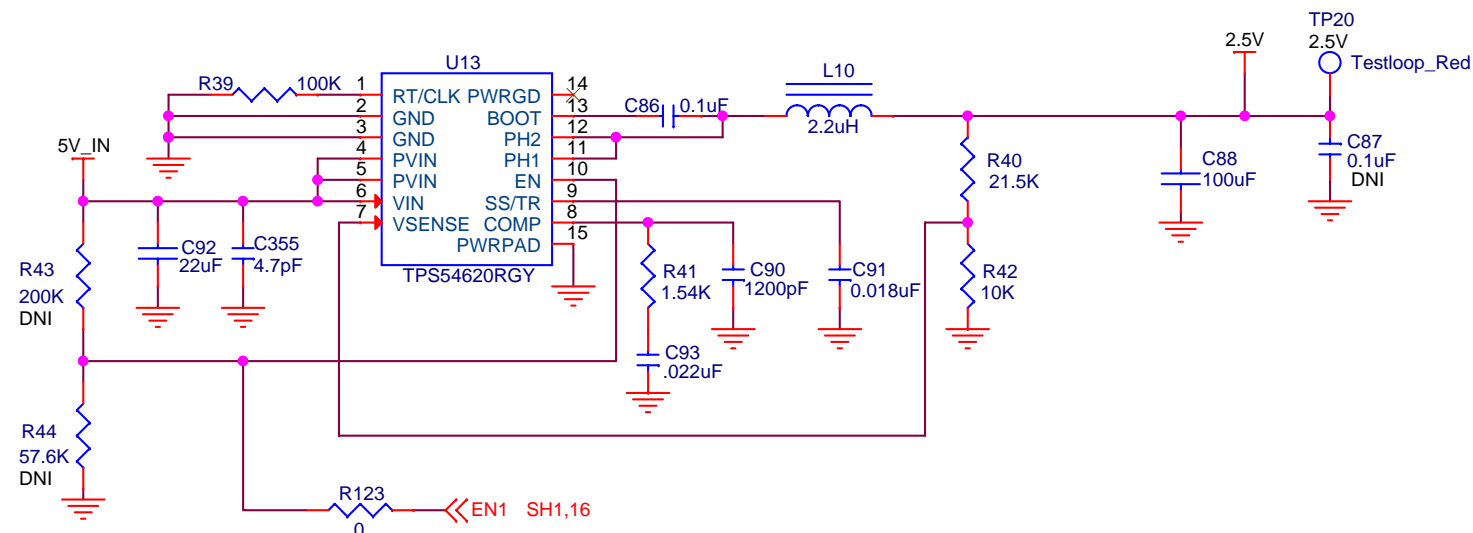
Title		
POWERS 0.9V, 1.1V, 1.5V, 1.8V		
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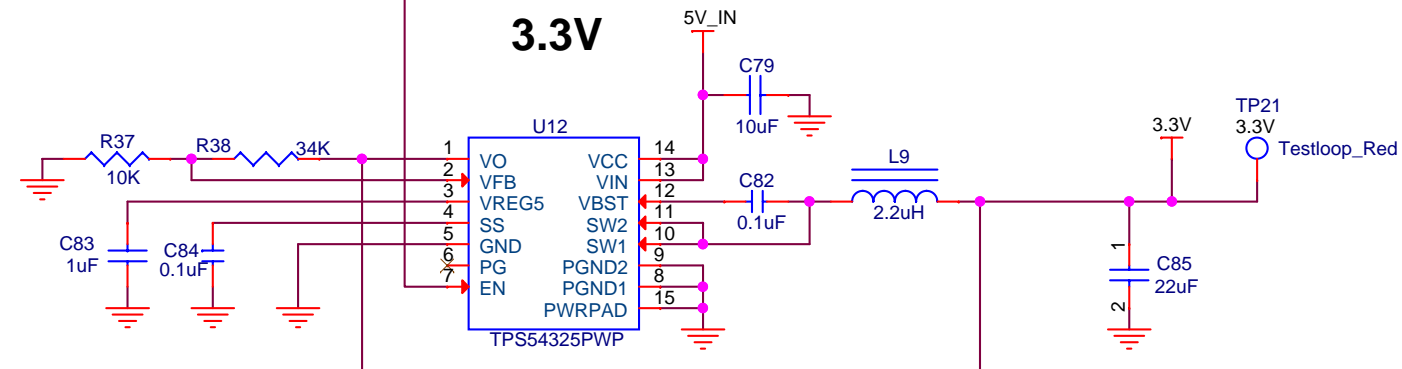
2.5V, 3.0V, 3.3V, 5V



2.5V

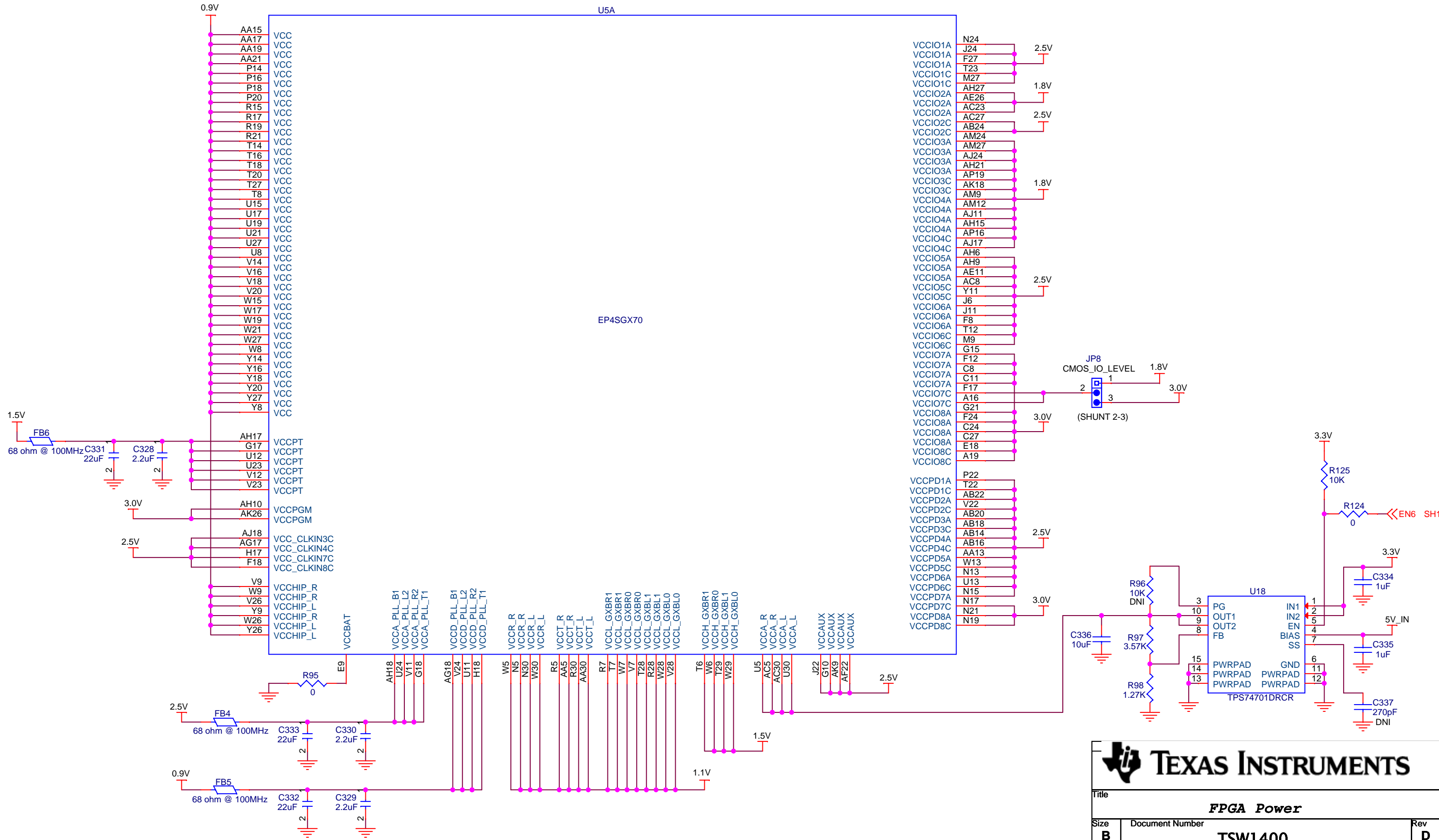


3.3V

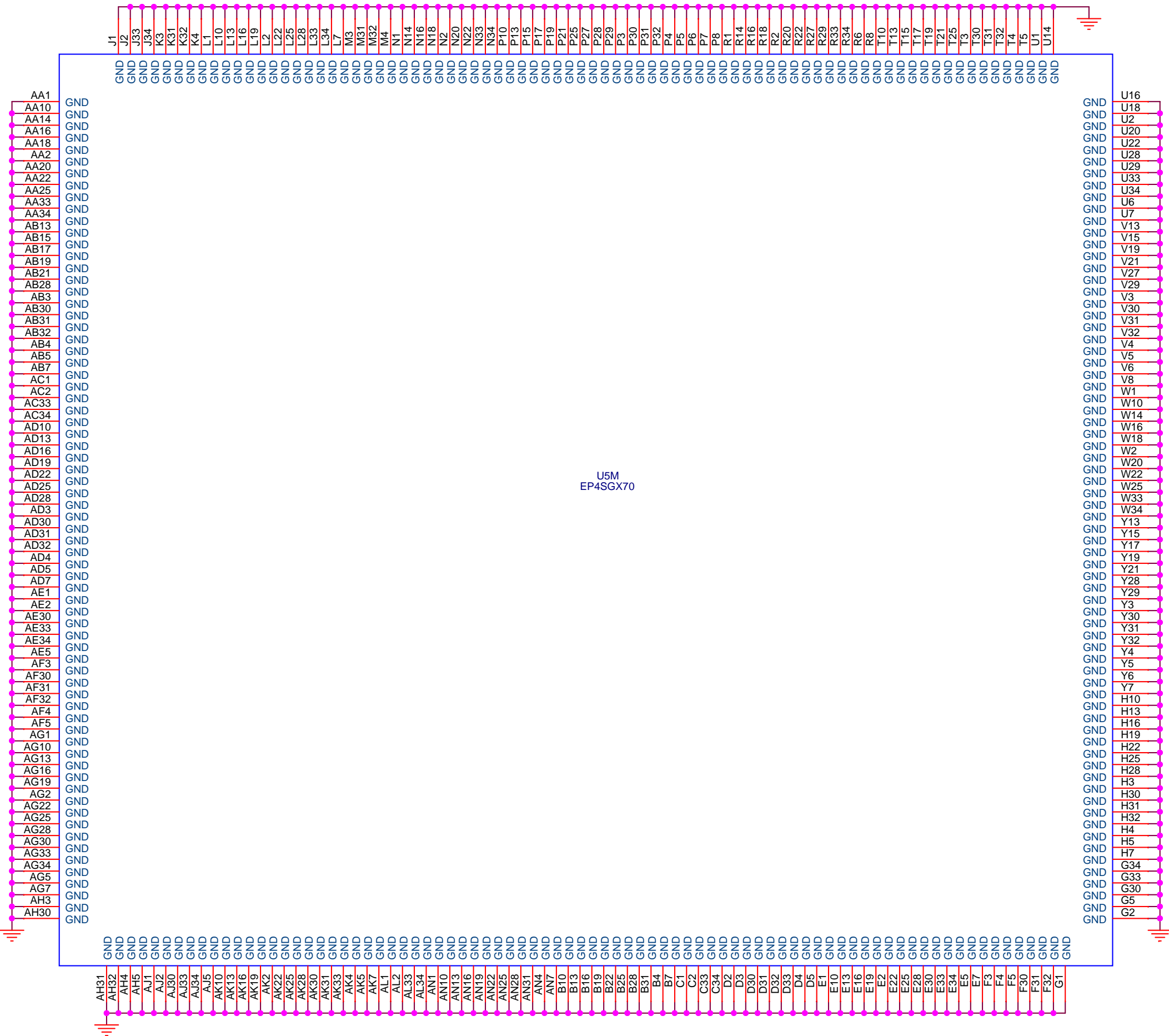



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FPGA Power



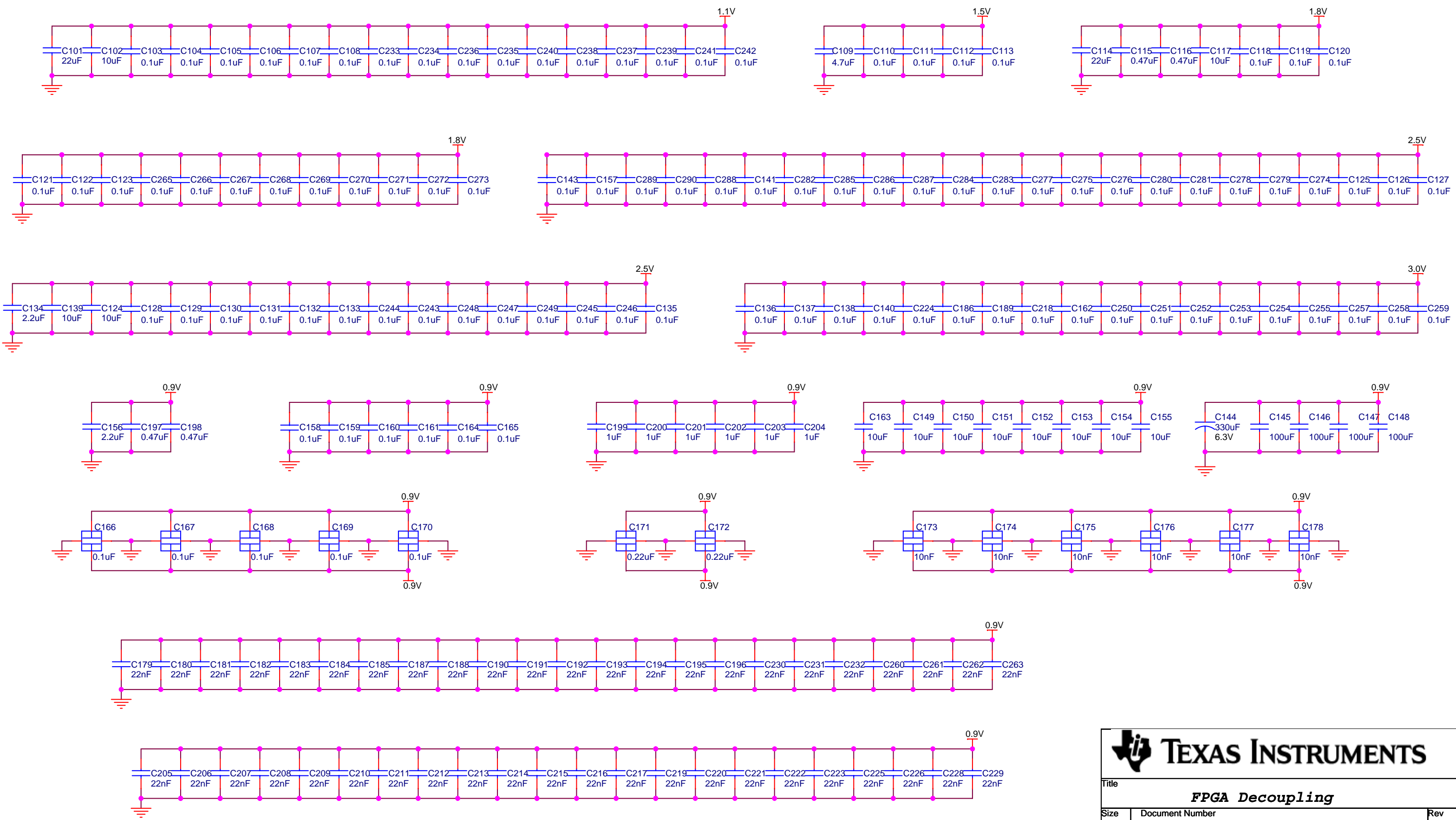
FPGA Ground



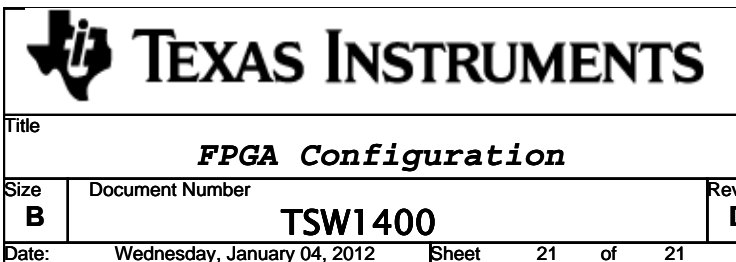
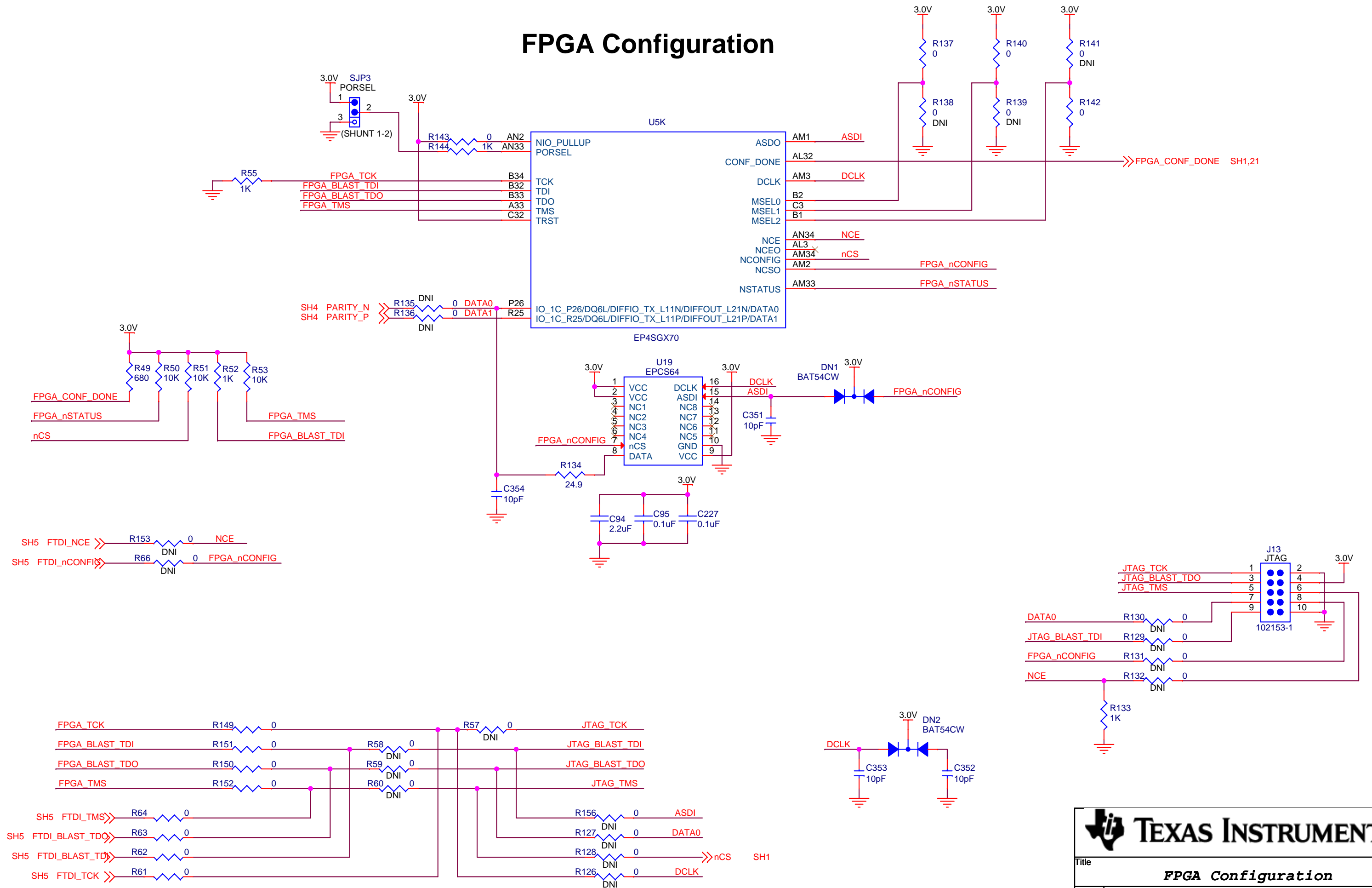
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FPGA Decoupling



FPGA Configuration



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